

Appln. No. 09/920,192

Attorney Docket No. 10541-609

II. Listing of Claims

1-7. (Cancelled).

8-20. (Withdrawn).

21. (Currently Amended): An electronic circuit assembly for connecting an electronic component thereto, comprising:

an electrically insulative substrate;

a tri-metallic sheet having a first layer of a first metal, a second layer of a second metal and a third layer of the first metal;

at least two mounting pads made from the first layer and disposed on said substrate in matched relation with respective terminations of the electronic component; and

at least one metallic bump made from the second layer and attached to each of the at least two mounting pads within a projected footprint of the electronic component.

22. (Currently Amended) ~~An~~ The electronic circuit assembly according to claim 21, wherein said at least one bump on each of the at least two mounting pads is/are arranged generally symmetrically thereon with respect to a central longitudinal axis of said projected footprint.

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23. (Currently Amended) ~~An~~ The electronic circuit assembly according to claim 21, wherein said mounting pads are made of a first metal and said metallic bumps are made of a second metal.

24. (Currently Amended) ~~An~~ The electronic circuit assembly according to claim 23, wherein said first metal is copper and said second metal is aluminum.

25. (Currently Amended): An electronic circuit assembly, comprising:

an electrically insulative substrate;

a tri-metallic sheet having a first layer of a first metal, a second layer of a second metal and a third layer of the first metal mounted to the substrate;

at least two mounting pads made from the first layer ~~disposed on said~~ substrate;

at least one metallic bump made from the second layer and attached to a top surface of each of the at least two mounting pads;

an electronic component having at least two terminations thereon, said component being disposed such that each termination rests atop a respective one of said at least two mounting pads in contact with said at least one metallic bump atop each pad; and

a joint of electrically conductive bonding material connecting each termination with a respective one of said at least two mounting pads.

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26. (Currently Amended) ~~AA~~ The electronic circuit assembly according to claim 25, wherein said mounting pads are made of copper and said bumps are made of aluminum.

27. (Currently Amended) ~~AA~~ The electronic circuit assembly according to claim 25, wherein said bonding material is solder or electrically conductive adhesive.

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26. (Currently Amended) ~~An~~ The electronic circuit assembly according to claim 25, wherein said mounting pads are made of copper and said bumps are made of aluminum.

27. (Currently Amended) ~~An~~ The electronic circuit assembly according to claim 25, wherein said bonding material is solder or electrically conductive adhesive.